



# Types AC, BC Thick Film Chip Resistors

Type AC – 1/10 Watt at 70°C

Type BC – 1/8 Watt at 70°C

±5%, 300 PPM/°C

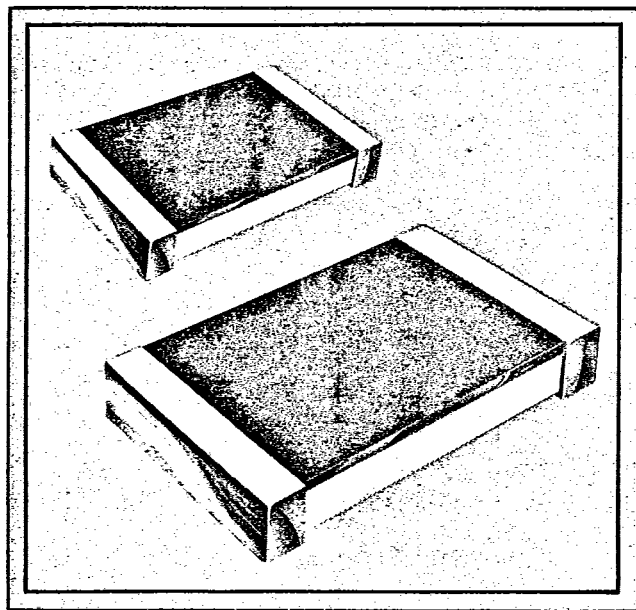
±2%, ±5%, 200 PPM/°C

±1%, 100 PPM/°C

Zero Ohm Jumper

## FEATURES

- Standard Sizes: AC – 2.10 x 1.25 x 0.5 mm (0805)  
BC – 3.20 x 1.60 x 0.6 mm (1206)
- Thick Film Resistance Element
- High Purity Alumina Substrate
- Glass Passivated
- Laser Trimmed
- Tight TCR
- Wrap-Around Termination
- Inner Electrode Protection
- Wave or Reflow Solderable
- Surface Mountable
- Nickel Barrier Construction



## Outstanding Characteristics

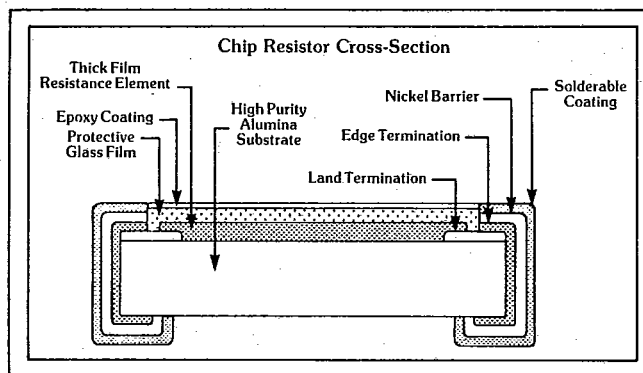
**Small standard size** — Utilizes the internationally standardized 3.20 x 1.60 x 0.6 mm and 2.10 x 1.25 x 0.5 mm sizes. Compatible with automatic placement equipment for surface mount assemblies and hybrid circuits.

**Proven technology** — Thick film resistance element on high purity alumina substrate. Over 20 years of technological experience in ink formulation and thick film resistor manufacturing.

**Precision performance** — Excellent performance characteristics provided by the thick film resistance material, resulting in tight tolerance, tight TCR and outstanding environmental performance.

**Cost effective** — Enables size reduction, weight reduction, reduced total material cost and reduced assembly cost.

**High reliability** — Automated manufacturing and process control, 200% electrical inspection and packaging integrity assure high reliability.



## Standard Specifications

Resistor tolerance — ±1%, ±2% or ±5%.

Temperature coefficient of resistance — ±100 ppm/°C, ±200 ppm/°C or ±300 ppm/°C, ±50 ppm/°C available on ±1% tolerance.

Operating temperature range — -55°C to ±125°C.

Power dissipation ratings— Chip resistor type designation	Power dissipation rating up to 70°C ambient ■
AC—2.10 × 1.25 mm	100mW
BC—3.20 × 1.60 mm	125mW ■

■ At 70°C power derates linearly from full rated power to 0 wattage at 125°C.

■ Optional 1/4 watt power rating permissible when resistor temperature is maintained at less than 150°C and the substrate temperature at the chip base is less than 120°C.

Nominal resistance ranges —

5% — 10 ohms to 2.2 megohms, E24 series.

2% — 22 ohms to 2.2 megohms, E24 series.

1% — 49.9 ohms to 2.21 megohms, E96 series.

Zero ohm jumper — .05 ohms max.

Rated continuous working voltage (RCWV) — Rated continuous working voltage (RCWV) based on nominal resistance (R) in ohms, is  $\sqrt{\text{rated power} \times R}$  or 150 volts for Type AC and 200 volts for Type BC, whichever is less.

User-trimmable option — Allen-Bradley chip resistors can be designed to permit the user to actively calibrate the resistor in a system. Resistors can be laser trimmed under actual circuit operating conditions, providing active system adjustment capability.

## Standard Resistance Values

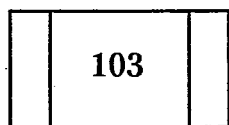
### Series E24 — 5%

10	22	47
11	24	51
12	27	56
13	30	62
15	33	68
16	36	75
18	39	82
20	43	91

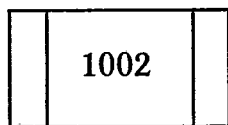
### Series E96 — 1%

10.0	13.0	16.9	22.1	28.7	37.4	48.7	63.4	82.5
10.2	13.3	17.4	22.6	29.4	38.3	49.9	64.9	84.5
10.5	13.7	17.8	23.2	30.1	39.2	51.1	66.5	86.6
10.7	14.0	18.2	23.7	30.9	40.2	52.3	68.1	88.7
11.0	14.3	18.7	24.3	31.6	41.2	53.6	69.8	90.9
11.3	14.7	19.1	24.9	32.4	42.2	54.9	71.5	93.1
11.5	15.0	19.6	25.5	33.2	43.2	56.2	73.2	95.3
11.8	15.4	20.0	26.1	34.0	44.2	57.6	75.0	97.6
12.1	15.8	20.5	26.7	34.8	45.3	59.0	76.8	
12.4	16.2	21.0	27.4	35.7	46.4	60.4	78.7	
12.7	16.5	21.5	28.0	36.5	47.5	61.9	80.6	

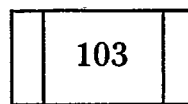
## Optional Marking Diagrams



Type BC  
5% marking



Type BC  
1% marking



Type AC  
5% marking



Type AC  
1% marking  
Consult Factory

Marking — Standard marking is no marking on the chip itself. Marked chips are available. All other required marking is on the unit package.

Marking explanation — 5% tolerance: 3 digit, first two digits significant, third digit is number of zeros. Letter R is decimal point.

Packaging — Standard packaging is 8 mm tape reel per EIA 481. Standard quantities are — Paper tape: 5,000 or 10,000 per reel. Embossed tape: 4,000 or 8,000 per reel. Bulk: 2,500 per plastic bag.

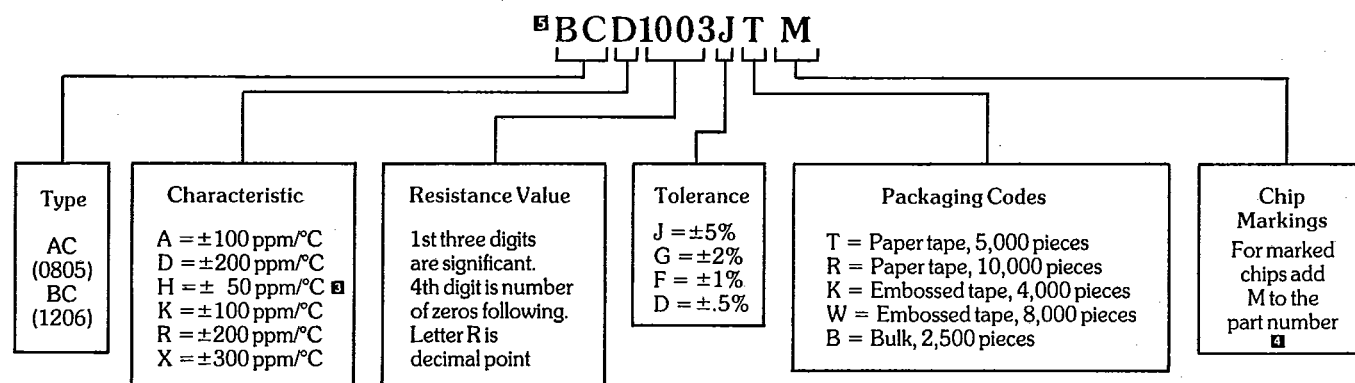
1% tolerance: Four digit, first three digits significant, third digit is number of zeros. Letter R is decimal point.

**Performance Characteristics**

TYPE		BCD BCK BCH	BCR/ACR BCA/ACA	BCX/ACX
Resistance Range (by Type)		10 Ohms to 2.2 Megohms 49.9 Ohms to 2.2 Megohms 499 Ohms to 499K Ohms	100 Ohms to 1 Megohm "	10 Ohms to 2.2 Megohms
PERFORMANCE TEST	TEST METHOD	REQUIREMENT (MAX LIMIT)		
Temperature Coefficient (by Type)	MIL-STD-202F, Method 304 -55°C to +125°C	±200 ppm/°C ±100 ppm/°C ±50 ppm/°C	±200 ppm/°C ±100 ppm/°C	±300 ppm/°C
Thermal Shock	MIL-STD-202F, Method 107 5 cycles. -55°C to +125°C	±0.5% max.	±0.5% max.	±1.0% max.
Low Temperature Operation	MIL-R-55342C, Para. 4.7.4 One hour at -55°C followed by 45 minutes RCWV	±0.5% max.	±0.5% max.	±0.5% max.
Short Time Overload	MIL-R-55342C, Para. 4.7.5 2.5 times RCWV for 5 seconds. 400 volt max.	±0.5% max.	±1.0% max.	±1.0% max.
High Temperature Exposure	MIL-R-55342C, Para. 4.7.6 125°C for 100 hours	±1.0% max.	±1.0% max.	±2.0% max.
Resistance to Bonding Exposure	MIL-R-55342C, Para. 4.7.7 Soldered to test board at 260°C for 10 seconds	±0.25% max.	±0.5% max.	±1.0% max.
Moisture Resistance	MIL-STD-202F, Method 106 10 cycles. Total 240 hours	±0.5% max.	±1% max.	±2.0% max.
Life	MIL-STD-202F, Method 108A 2000 hours at 70°C. RCWV intermittent	±1.0% max.	±2.0% max.	±3.0% max.
Solderability	MIL-STD-202F, Method 208 230°C for 5 seconds	95% min. coverage	95% min. coverage	95% min. coverage
Terminal Adhesion	MIL-R-55342C, Para. 4.7.12 15 gram pull for 30 seconds	15 grams min.	15 grams min.	15 grams min.
Terminal Strength, Push	1.2 Kg push for 60 seconds from underside of mounted unit	±1.0% max.	±1.0% max.	±1.0% max.
Bending	Unit mounted in center of 90 mm board length, deflected 5 mm in either direction for 10 seconds	±1.0% max.	±1.0% max.	±1.0% max.

**Note:** All measurements to be made in accordance with the general requirements of MIL-R-55342C, unless otherwise noted. All performance limits are understood as reading ± (x +0.05 ohms). For tests requiring mounted units, the substrate shall be G-10 epoxy board, 0.062 inches thick, or equivalent. Test mounting pads shall be 1.0 mm wide, spaced 1.75 mm apart, with substrate at least 4 times the resistor area for each test unit.

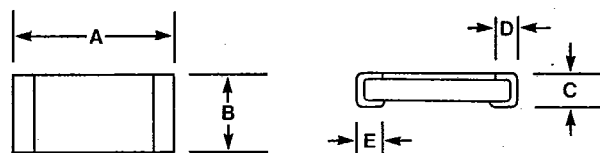
**Explanation of Part Numbers**



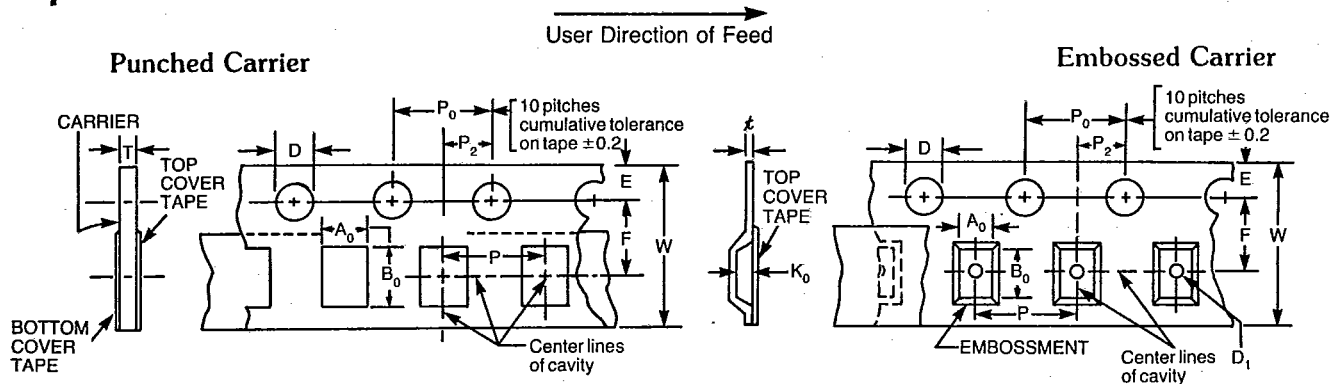
# DIMENSIONS

## Chip

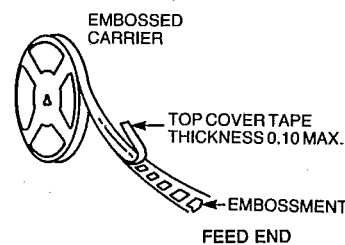
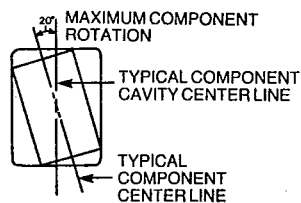
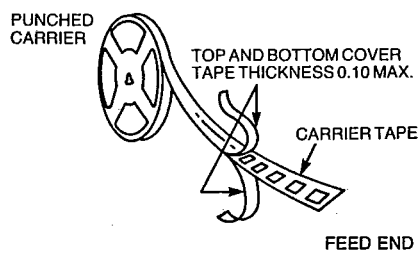
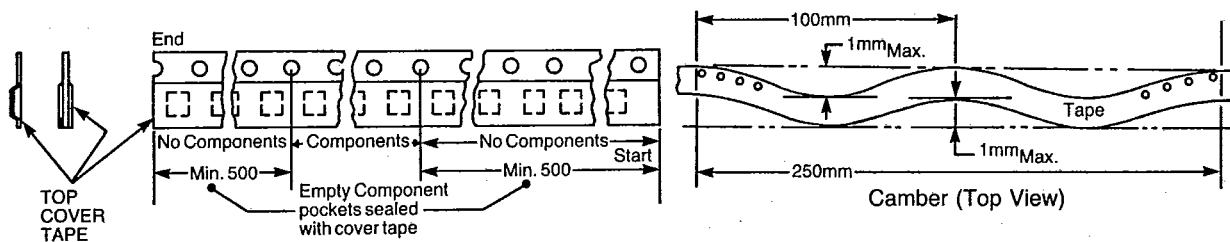
Dimension	A	B	C	D	E
Type AC	2.1±.15	1.25±.15	.5±.15	.38±.13	.38±.13
Type BC	3.2±.15	1.6±.15	.6±.15	.38±.13	.38±.13



## Tape

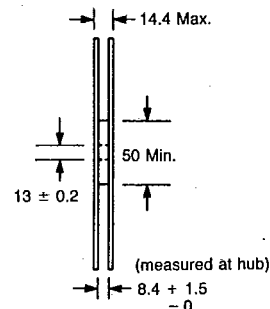
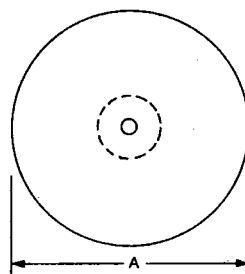


Dimension	W	F	E	P, P <sub>0</sub>	P <sub>2</sub>	D	D <sub>1</sub> MIN	A <sub>0</sub>	B <sub>0</sub>	K <sub>0</sub>	T	t MIN
Type AC	8.0±.3	3.5±.05	1.75±.05	4.0±.10	2.0±.05	1.5 <sup>+0.10</sup> <sub>-.0</sub>	1.0	1.45-1.60	2.30-2.45	.70-.85	.70-.85	.40
Type BC	8.0±.3	3.5±.05	1.75±.05	4.0±.10	2.0±.05	1.5 <sup>+0.10</sup> <sub>-.0</sub>	1.0	1.80-1.95	3.40-3.55	.80-.95	.80-.95	.40



## Reel

"A" Maximum	Component/Reel	
	Paper	Embossed
178 mm	5,000	4,000
254 mm	10,000	8,000



All dimensions in millimeters.